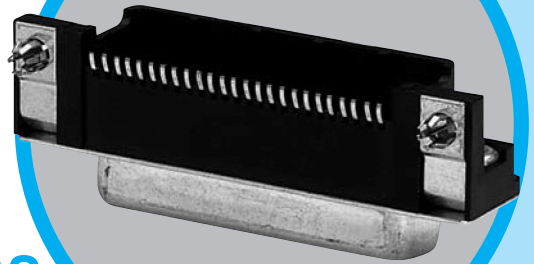


SM2

D-Sub connectors - Stamped and Formed Contacts



SURFACE MOUNT CONNECTORS

CHARACTERISTICS

Specifications

- Connectors according to MIL C24308 - NFC 93425-HE5

Materials and Platings	
Shells	Steel with tin plating
Insulator	High temperature (peak at 260°C) glass-filled PA6T
Socket contact	Stamped and formed brass, selected gold in mating area; 2.54µm (100µ") min. tin on termination area, with entire contact under-plated 1.27µm (50µ") min. nickel
Rear insert	Brass, 3µm to 5µm (118µ" to 197µ") tin over nickel 2µm to 3µm (78µ" to 118µ")
Boardlock	Tin plating 4µm to 6µm (157µ" to 236µ") over nickel 2µm to 3µm (78µ" to 118µ"), insertion force: Low Insertion Force = LIF (bronze) Zero Insertion Force = ZeFo (brass)
Screwlock	Brass, 6µm to 10µm (236µ" to 394µ") tin over nickel 2µm to 3µm (78µ" to 118µ")
Grounding	Grounding strap: brass, 4µm to 6µm tin over nickel 2µm to 3µm (78µ" to 118µ")

Electrical Data	
Current rating	3A
Voltage rating	300V AC/rms 50Hz
Withstanding voltage	1000V AC/rms 50Hz for one minute
Insulation resistance	5000MΩ
Contact resistance	10mΩ max

Climatic Data	
Operating temperature	-55°C, peak at 125°C
Damp heat	56 days (40°C - 95% HR)

Mechanical Data	
Single contact insertion force	1.2N < F < 2.5N
Single contact withdrawal force	0.4N min
LIF boardlock	8N max per connector
Coplanarity of contacts	0.2mm (.008") max

Mating and unmating force
Unit: N

No. of Cts	Mate (max)	Unmate (min)
9 (size E)	30	3.5
15 (size A)	50	4.5
25 (size B)	83	8.0

DESCRIPTION

Amphenol SMT D-Sub is offered in right angle receptacle with brackets as an industry standard for I / O connections.

Boardlock features:

- LIF (Low Insertion Force) boardlock especially designed to be fully compatible with pick and place machine.
- ZeFo (Zero Force Insertion) boardlock has been designed so that once placed and expanded, secures a safe locking.

Designed for
Pick and Place
SMT process

APPLICATIONS

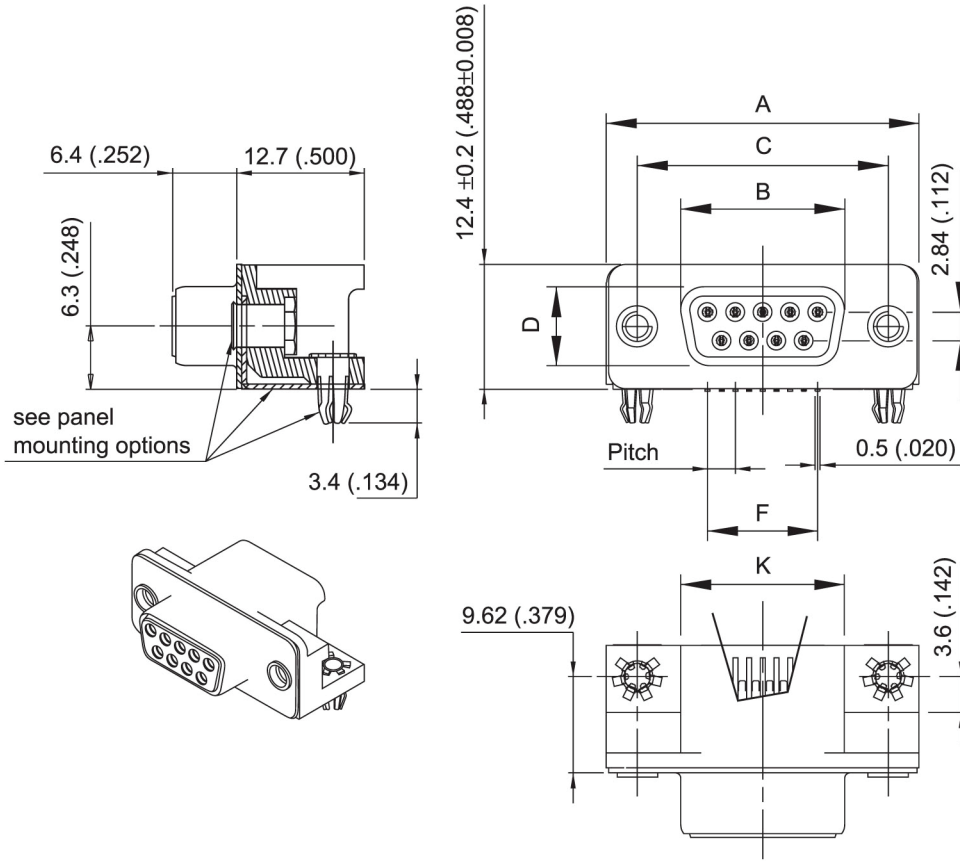
- Industrial
- Telecom
- Any industry standard I / O connections



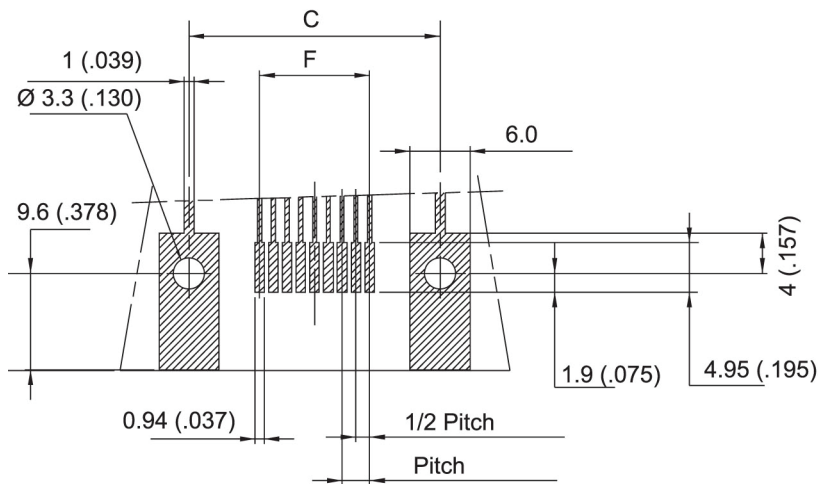
Amphenol

SM2 / E2

Shell Size Dimensions



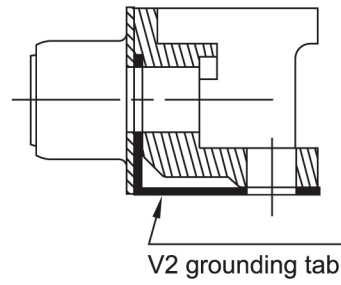
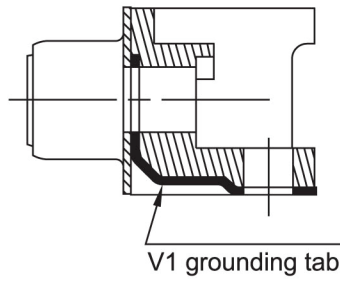
PCB LAYOUT



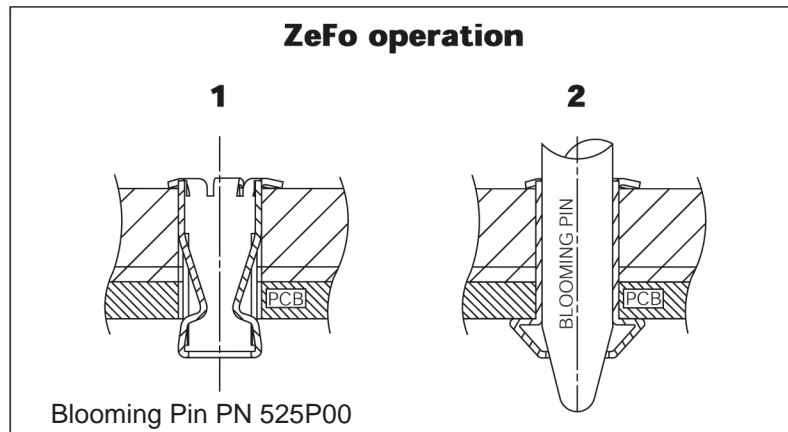
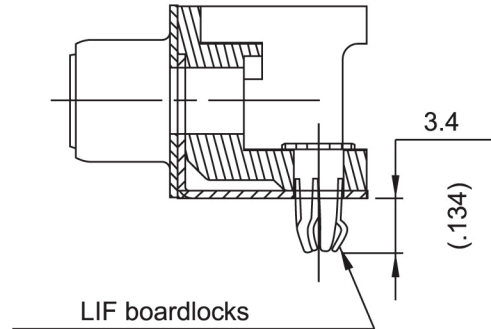
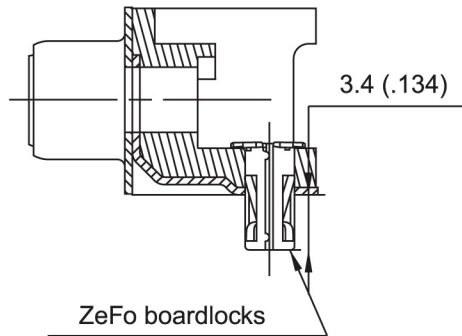
SHELL SIZE	mm (inch)						
	A	B	C	D	PITCH	F	K
	+0.05 (.002) -0.1 (.004)	0 -0.2 (.008)	±0.1 (.004)	0 -0.25 (.01)			
E	31.15 (1.226)	16.4 (.645)	25 (.984)	8.03 (.316)	2.74 (.1078)	10.97 (.432)	16.3 (.642)
A	39.4 (1.551)	24.8 (.976)	33.3 (1.311)	8.03 (.316)	2.74 (.1078)	19.2 (.756)	24.6 (.968)
B	53.3 (2.098)	38.5 (1.515)	47 (1.850)	8.03 (.316)	2.76 (.1086)	33.12 (1.304)	38.3 (1.508)

Panel mounting option

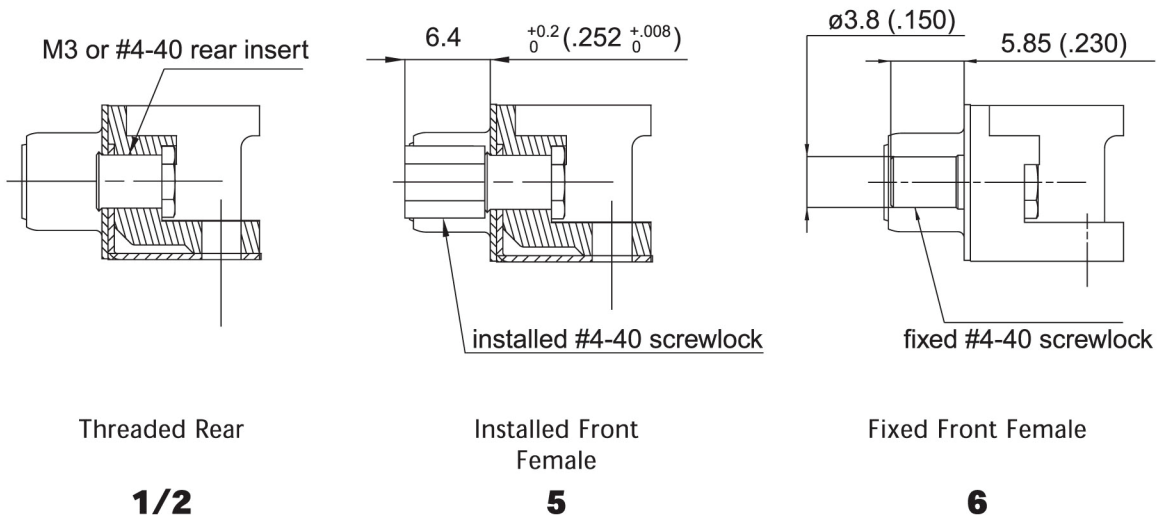
GROUNDING TABS:



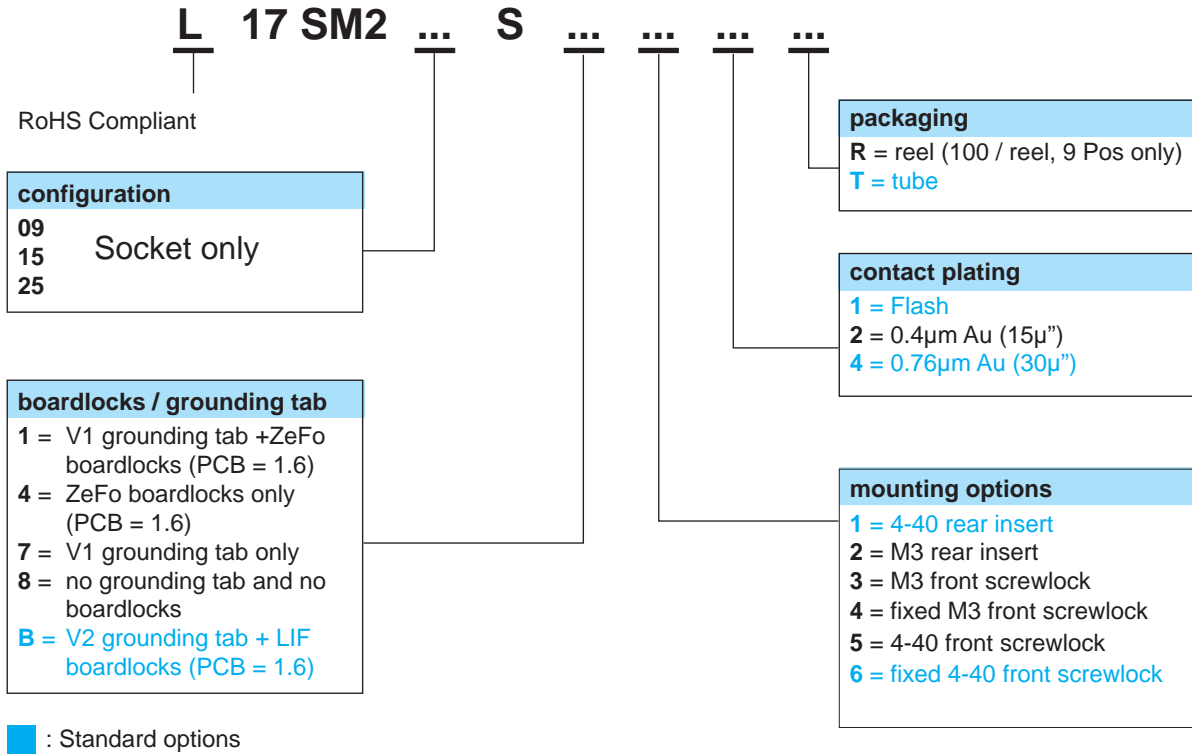
BOARDLOCKS:



FLANGES ACCESSORIES:



How to order



For special request, please consult factory

Memo

Do not hesitate to contact us for further information

Amphenol

Amphenol IT & Communication Products

Block A3/A4, The 4th Industrial District of Industrial Headquarters, Dong Keng Road Gong Ming Town, Shen Zhen China
 Fax:+86(0)755 2754 9955

Technical Support

Tel:+86(0)755 2717 7945
 Info-dsub@amphenol.com.cn
 http://www.dsubconnector.com